

CER Series
Controlled ESR Capacitors

Type: CERB (C1608

Issue date: April 2011

TDK MLCC US Catalog



REMINDERS

Please read before using this product

SAFETY REMINDERS



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CER Series

Controlled ESR Capacitors

Type: CERB (C1608), CERD (C2012)

Features



- This is a ceramic chip capacitor with the additional function of controlling (assures design of) the ESR (Equivalent Series Resistance) value as desired.
- This function enables control of voltage change, which can occur between the power source and the CPU, by controlling the impedance of capacitors located around the CPU.
- This enables a reduction in the number of parts used and contributes to cost savings, set downsizing, and upgrading quality.
- The replacement of existing products is easy because the mounting method is the same as products with two terminals.

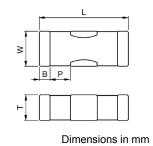
Applications



- PC server
- · Power decoupling and smoothing
- Voltage regulator
- Output filters
- Plane termination
- USB damping circuit
- Tantalum capacitor replacement

Shape & Dimensions







Sarias Nama

CERD 2J X5R 0G 106 M T XXXX

| Series Mairie | | |
|---------------|-----------------|-----------------|
| Case Code | Length | Width |
| CERB | 1.60 ± 0.20 | 0.80 ± 0.10 |
| CERD | 2.00 ± 0.20 | 1.25 ± 0.20 |
| ESR — | | |
| | | |
| ESR Code | ESR Value | |
| 1C | 20mO | |

| 1C | 20mΩ | |
|----|---------|---|
| 1F | 35mΩ | |
| 1J | 50mΩ | |
| 2A | 100mΩ | _ |
| 2C | 200mΩ | _ |
| 2J | 500mΩ | |
| 2M | 650mΩ | |
| 3U | 1,200mΩ | _ |

Temperature Characteristic

| Temperature | Capacitance | Temperature |
|-----------------|-------------|--------------|
| Characteristics | Change | Range |
| Y5D | + 15% | -55 to +85°C |

Rated Voltage (DC)

| | ` ' |
|--------------|--------------|
| Voltage Code | Voltage (DC) |
| 0G | 4V |

Internal Codes Packaging Style

| Packaging Code | Style |
|----------------|-------------|
| Т | Tape & Reel |

Capacitance Tolerance

| Tolerance Code | Tolerance | |
|----------------|-----------|--|
| M | ± 20% | |

Nominal Capacitance (pF)

The capacitance is expressed in three digit codes and in units of pico Farads (pF). The first and second digits identify the first and second significant figures of the capacitance. The third digit identifies the multiplier. R designates a decimal point.

| 0R5 | 0.5pF |
|-----|-------------------|
| 010 | 1pF |
| 102 | 1,000pF (1nF) |
| 105 | 1,000,000pF (1µF) |
| | |





CERB [EIA CC0603]

Class 2 (Temperature Stable)

Temperature Characteristics: X5R (-55 to +85°C, ±15%)

| TDK Part Number (Ordering Code) | ESR | Temperature Characteristics | Rated Voltage | Capacitance (pF) | Capacitance Tolerance | Thickness (mm) |
|------------------------------------|-------------------------------|--------------------------------|------------------|---------------------|--------------------------|-------------------|
| CERB2CX5R0G105M | $200~\text{m}\Omega\pm30\%$ | X5R | 4V | 1,000,000 | ± 20% | 0.80 ± 0.10 |
| CERB2MX5R0G105M | $650~\text{m}\Omega~\pm~30\%$ | X5R | 4V | 1,000,000 | ± 20% | 0.80 ± 0.10 |
| CERB3UX5R0G105M | 1,200 mΩ ± 30% | X5R | 4V | 1,000,000 | ± 20% | 0.80 ± 0.10 |



CERD [EIA CC0805]

Class 2 (Temperature Stable)

Temperature Characteristics: X5R (-55 to +85°C, ±15%)

| TDK Part Number (Ordering Code) | ESR | Temperature Characteristics | Rated Voltage | Capacitance (pF) | Capacitance Tolerance | Thickness (mm) |
|------------------------------------|-------------------------------|--------------------------------|------------------|---------------------|--------------------------|-------------------|
| CERD1CX5R0G106M | $20 \text{ m}\Omega \pm 30\%$ | X5R | 4V | 10,000,000 | ± 20% | 0.85 ± 0.15 |
| CERD1JX5R0G106M | $50 \text{ m}\Omega \pm 30\%$ | X5R | 4V | 10,000,000 | ± 20% | 0.85 ± 0.15 |
| CERD2AX5R0G106M | 100 m Ω ± 30% | X5R | 4V | 10,000,000 | ± 20% | 0.85 ± 0.15 |
| CERD2CX5R0G106M | $200~\text{m}\Omega\pm30\%$ | X5R | 4V | 10,000,000 | ± 20% | 0.85 ± 0.15 |
| CERD2JX5R0G106M | $500~\text{m}\Omega\pm30\%$ | X5R | 4V | 10,000,000 | ± 20% | 0.85 ± 0.15 |



/ Capacitor



| No. | ltem | Performance | | Test or Inspection Method | | ethod | |
|-----|---|--|--|--|---|---|--|
| 1 | External Appearance | No defects which may affect performance. | | Inspect | with magnifying (| glass (3×). | |
| 2 | Insulation Resistance | 100MΩ•μF min. | | Apply ra | Apply rated voltage for 60s. | | |
| 3 | ESR | Code 1C 1F 1J 2A 2C 2J | ESR 20 mΩ 35 mΩ 50 mΩ 100 mΩ 200 mΩ 500 mΩ | —————————————————————————————————————— | Measur | e self resonant fr | equency by network analyzer |
| | | 3U | 1,200 mΩ | _ | | | |
| 4 | Voltage Proof | Withstand test voltage without insulation breakdown or other damage. | | | |) shall be applied for 1 to 5s. ent shall not exceed 50mA. | |
| 5 | Capacitance | Within the | e specified toleran | ce. | | uring Frequency 1kHz±10% | Measuring Voltage 1.0±0.2V _{rms} |
| 6 | Dissipation Factor | Tempera X5R | Temperature Characteristic D.F. X5R 0.10 max. | | See No | .4 in this table for | measuring condition. |
| 7 | Temperature Characteristics of Capacitance (Class 2) | | nce Change (%) o Voltage Applied X5R: ± 15% | | the follofor each ΔC be of Step 1 2 3 4 | wing table after to step. calculated ref. ST Temperature (°C Reference temp. Min. operating ter Reference temp. Max. operating te |) ± 2 mp. ± 3 ± 2 |
| 8 | Robustness of Terminations | | f termination comi | | | lix 2) and apply a | tors on P.C. board (shown in pushing force of 5N with 5N P.C.Board |



| No. | ltem | Performance | | Test or Inspection Method |
|-----|--|---|--|---|
| 9 | Bending | ding No mechanical damage. | | Glue and wave solder the capacitor on P.C. board (shown in Appendix 1) and bend it for 1mm. |
| | | | | 50 F R230 Unit: mm |
| 10 | termination. 25% may have pin holes | | Completely soak both terminations in solder at $235\pm5^{\circ}\text{C}$ for $2\pm0.5\text{s}$. | |
| | | or rough spots but one spot. Ceramic | not concentrated in | Solder : H63A (JIS Z 3282) |
| | | sections" shall not | be exposed due to | Flux: Isopropyl alcohol (JIS K 8839) |
| | | melting or shifting material. | of termination | Rosin (JIS K 5902) 25% solid solution. |
| 11 | Resistance to so | | A section | Completely soak both terminations in solder at 260 ± |
| | External | No cracks are allo | wed and terminations | 5°C for 5 ± 1s. |
| | appearance | | Preheating condition Temp.: 150 ± 10°C | |
| | Capacitance Characteristics Change from the value before test Class 2 | | | Time: 1 ~ 2min. |
| | | | | Flux: Isopropyl alcohol (JIS K 8839) |
| _ | D.F. (Class 2) | Meet the initial spec. | | Rosin (JIS K 5902) 25% solid solution. |
| | Insulation | Meet the initial spe | | Solder : H63A (JIS Z 3282) |
| | Resistance | weet the initial spe | | Leave the capacitor in ambient conditions for 48 \pm 4h |
| | Voltage proof No insulation breakdown or other damage. | | kdown or other | before measurement. |
| | | /ibration | | Solder the capacitors on P.C. board (shown in |
| 12 | Vibration | | | |
| 12 | Vibration External | No mechanical da | mage. | Appendix 2) before testing. |
| 12 | | No mechanical da | mage. | Vibrate the capacitor with amplitude of 1.5mm P-P |
| 12 | External | No mechanical da | Change from the value before test | Vibrate the capacitor with amplitude of 1.5mm P-P changing the frequencies from 10Hz to 55Hz and back to 10Hz in about 1min. |
| 12 | External appearance | | Change from the | Vibrate the capacitor with amplitude of 1.5mm P-P changing the frequencies from 10Hz to 55Hz and back |





| No. | Item | Item Performance | | | Test or Inspection Method | | | |
|-----|---|---|-----------------------------------|--|---|---------------------------|--|--|
| 13 | Temperature cycle External No mechanical damage. appearance | | | Reflow solder the capacitors on a P.C. board (shown in Appendix 2) before testing. Expose the capacitor in the conditions in step 1 | | | | |
| | Capacitance | Characteristics | Change from the value before test | through step 4, and repeat 5 times consecutively Leave the capacitor in ambient conditions for 48: | | | | |
| | | Class 2 X5R | ± 12.5% | _ | before measurement. | | | |
| | D.F. (Class 2) | Meet the initial sp | Dec. | Step | Temperature (°C) | Time (min.) | | |
| | Insulation Resistance | Meet the initial sp | Dec. | 1 2 3 | $\begin{tabular}{ll} Min. operating temp. ± 3\\ Reference Temp.\\ Max. operating temp. ± 2\\ \end{tabular}$ | 30 ± 3 2 - 5 30 ± 2 | | |
| | Voltage Proof | No insulation breakdown or other damage. | | Reference Temp. | 2 - 5 | | | |
| 14 | Moisture Resista External appearance | ance (Steady State) No mechanical d | amage. | Append | solder the capacitor on P.C. ix 2) before testing. t temperature 40±2°C, 90 f | | | |
| | Capacitance | Characteristics Change from the value before test | | Leave the capacitor in ambient condition for 48±4h | | | | |
| | | Class 2 X5R | ± 25% | before measurement. | | | | |
| | D.F. (Class 2) | 200% of initial sp | ec. max. | | | | | |
| | Insulation Resistance | 10MΩ•μF min. | | | | | | |
| 15 | Moisture Resistance | | | Reflow solder the capacitors on P.C. board (shown in | | | | |
| | External appearance | No mechanical damage. | | Appendix 2) before testing. Apply the rated voltage at temperature 40±2°C and 9 to 95%RH for 500 +24,0h. | | | | |
| | Capacitance | Characteristics | Change from the value before test | | Charge/discharge current shall not exceed 50mA. | | | |
| | | Class 2 X5R | ± 25% | Leave th | Leave the capacitor in ambient conditions for 48±4h | | | |
| | D.F. (Class 2) | 200% of initial spec. max. | | before measurement. Voltage conditioning: Voltage treat the capacitors under testing temperature | | | | |
| | Insulation Resistance | 5MΩ•μF min. | | and voltage for 1 hour. Leave the capacitors in ambient condition for $48\pm4h$ before measurement. | | | | |
| | | | | Use this measurement for initial value. | | | | |





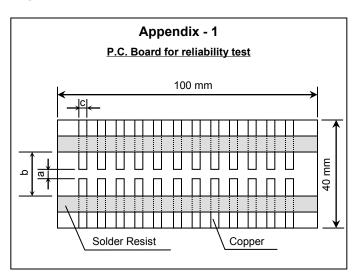
| ~ | | | | | | |
|-----|--------------------------|-----------------|-------------------|--|--|--|
| No. | . Item Performance | | е | Test or Inspection Method | | |
| 16 | Life | | | Reflow solder the capacitors on P.C. board (shown in Appendix 2) before testing. | | |
| | External | No mechanica | Il damage. | Appendix 2) before testing. | | |
| | appearance | | Ü | Apply rated voltage at $85\pm2^{\circ}$ C for 1,000 ±48 ,0h. | | |
| | Capacitance | Characteristic | Change from the | Charge/discharge current shall not exceed 50mA. | | |
| | | Characteristi | value before test | Leave the capacitor in ambient conditions for 48±4h | | |
| | | Class 2 X5F | ± 25% | before measurement. | | |
| | | | | Voltage conditioning: | | |
| | D.F. (Class 2) | 200% of initial | spec. max. | 3 | | |
| | 2.1.1 (0.000 2) | 2007001111110 | | Voltage treat the capacitors under testing temperature and voltage for 1 hour. | | |
| | la a dation | 40140 = | | Leave the capacitors in ambient condition for 48±4h | | |
| | Insulation Resistance | 10MΩ•μF min | | before measurement. | | |
| | Nesisialice | | | The difference of the 1984 of the | | |
| | | | | Use this measurement for initial value. | | |

^{*}As for the initial measurement of capacitors on number 7,11,12,13 and 14, leave capacitors at 150 –10,0° C for 1h and measure the value after leaving capacitors for 48±4h in ambient condition.





CER Series – Controlled ESR Capacitors



Appendix - 2

P.C. Board for bending test

100 mm

b

a

Copper

Material: Glass Epoxy (As per JIS C6484 GE4)

P.C. Board thickness: Appendix-2a

0.8mm

Appendix-1a, 1b, 2b

1.6mm

Copper (thickness 0.035mm)

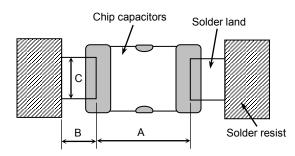
Solder resist

| | Case Code | Dimensions (mm) | | | |
|--------|-----------|-----------------|-----|-----|------|
| Series | JIS | EIA | а | b | С |
| CERA | C1005 | CC0402 | 0.4 | 1.5 | 0.5 |
| CERB | C1608 | CC0603 | 1.0 | 3.0 | 1.2 |
| CERD | C2012 | CC0805 | 1.2 | 4.0 | 1.65 |
| CERF | C3216 | CC1206 | 2.2 | 5.0 | 2.9 |



CER Series - Controlled ESR Capacitors

Recommended Soldering Land Pattern



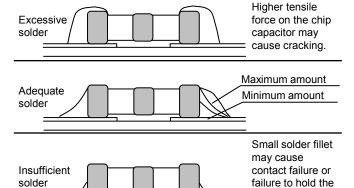
Reflow Soldering

Unit: mm

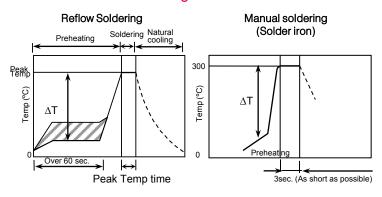
chip capacitor to the P.C. board.

| Туре | Α | В | D | F |
|--------|-------------|-----------|-----------|-----------|
| Symbol | [CC0402] | [CC0603] | [CC0805] | [CC1206] |
| Α | 0.3 - 0.5 | 0.6 - 0.8 | 0.9 - 1.2 | 2.0 - 2.4 |
| В | 0.35 - 0.45 | 0.6 - 0.8 | 0.7 - 0.9 | 1.0 - 1.2 |
| С | 0.4 - 0.6 | 0.6 - 0.8 | 0.9 - 1.2 | 1.1 - 1.6 |

Recommended Solder Amount



Recommended Soldering Profile



Recommended soldering duration

| Temp./ | Reflow Soldering | | |
|------------------|-------------------|-----------------|--|
| Dura. Solder | Peak temp (°C) | Duration (sec.) | |
| Sn-Pb Solder | 230 max. | 20 max. | |
| Lead-Free Solder | 260 max. | 10 max. | |

Recommended solder compositions Sn-37Pb (Sn-Pb solder)

Sn-3.0Ag-0.5Cu (Lead Free Solder)

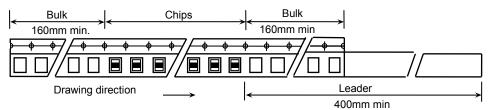
Preheating Condition

| Soldering | Temp. (°C) |
|------------------|------------|
| Reflow soldering | ΔT ≤ 150 |
| Manual soldering | ΔT ≤ 150 |

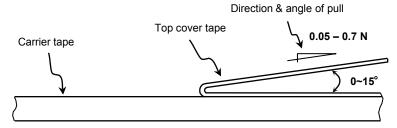


CER Series – Controlled ESR Capacitors

• Carrier Tape Configuration

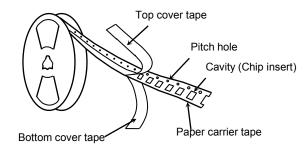


• Peel Back Force (Top Tape)



- Carrier tape shall be flexible enough to be wound around a minimum radius of 30mm with components in tape.
- The missing of components shall be less than 0.1%
- Components shall not stick to the cover tape.
- The cover tape shall not protrude beyond the edges of the carrier tape not shall cover the sprocket holes.

· Chip Quantity Per Reel and Structure of Reel



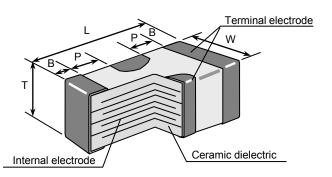
| | Case Code | | Chip Taping | Chip quantity (pcs.) | | |
|--------|-----------|--------|-------------|----------------------|---------------------|----------------------|
| Series | JIS | EIA | Thickness | Material | φ178mm (7") reel | φ330mm (13") reel |
| CERB | C1608 | CC0603 | 0.80 mm | Paper | 4,000 | 10,000 |
| CERD | C2012 | CC0805 | 085 mm | Paper | 4,000 | 10,000 |





CER Series – Controlled ESR Capacitors

Shape & Dimensions



| Case Code | | | Dimensions (mm) | | | | |
|-----------|-------|--------|-----------------|------|------|------|------|
| Series | JIS | EIA | L | W | Т | В | Р |
| CERB | C1608 | CC0603 | 1.60 | 0.80 | 0.80 | 0.25 | 0.25 |
| CERD | C2012 | CC0805 | 2.00 | 1.25 | 0.85 | 0.30 | 0.25 |

Environmental Information

TDK Corporation established internal product environmental assurance standards that include the six hazardous substances banned by the EU RoHS Directive¹ enforced on July 1, 2006 along with additional substances independently banned by TDK and has successfully completed making general purpose electronic components conform to the RoHS Directive².

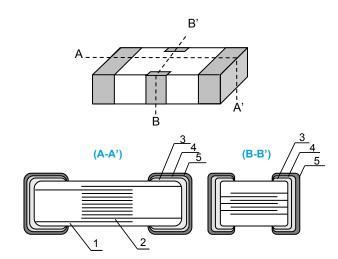
- Abbreviation for Restriction on Hazardous Substances, which refers to the regulation EU Directive 2002/95/EC on hazardous substances by the European Union (EU) effective from July 1, 2006. The Directive bans the use of six specific hazardous substances in electric and electronic devices and products handled within the EU. The six substances are lead, mercury, cadmium, hexavalent chromium, PBB (polybrominated biphenyls), and PBDE (polybrominated diphenyl ethers).
- This means that, in conformity with the EU Directive 2002/95/EC, lead, cadmium, mercury, hexavalent chromium, and specific bromine-based flame retardants, PBB and PBDE, have not been used, except for exempted applications.

For REACH (SVHC: 15 substances according to ECHA / October 2008): All TDK MLCC do not contain these 15 substances.

For European Directive 2000/53/CE and 2005/673/CE : Cadmium, Hexavalent Chromium, Mercury, Lead are not contained in all TDK MLCC.

For European Directive 2003/11/CE: Pentabromodiphenyl-ether, Octabromodiphenyl-ether are not contained in all TDK MLCC.

Inside Structure & Material System



| No. | NAME | MATERIAL | | |
|-----|--------------------|--------------------|--------------------|--|
| | | Class 1 | Class 2 | |
| (1) | Ceramic Dielectric | CaZrO ₃ | BaTiO ₃ | |
| (2) | Internal Electrode | Nickel (Ni) | | |
| (3) | | Coppe | er (Cu) | |
| (4) | Termination | Nickel (Ni) | | |
| (5) | | Tin | (Sn) | |